

SOT257-2

ceramic pin grid array package; 68 pins; body 27.9 x 27.9 x 2.4 mm

8 February 2016

Package information

1. Package summary

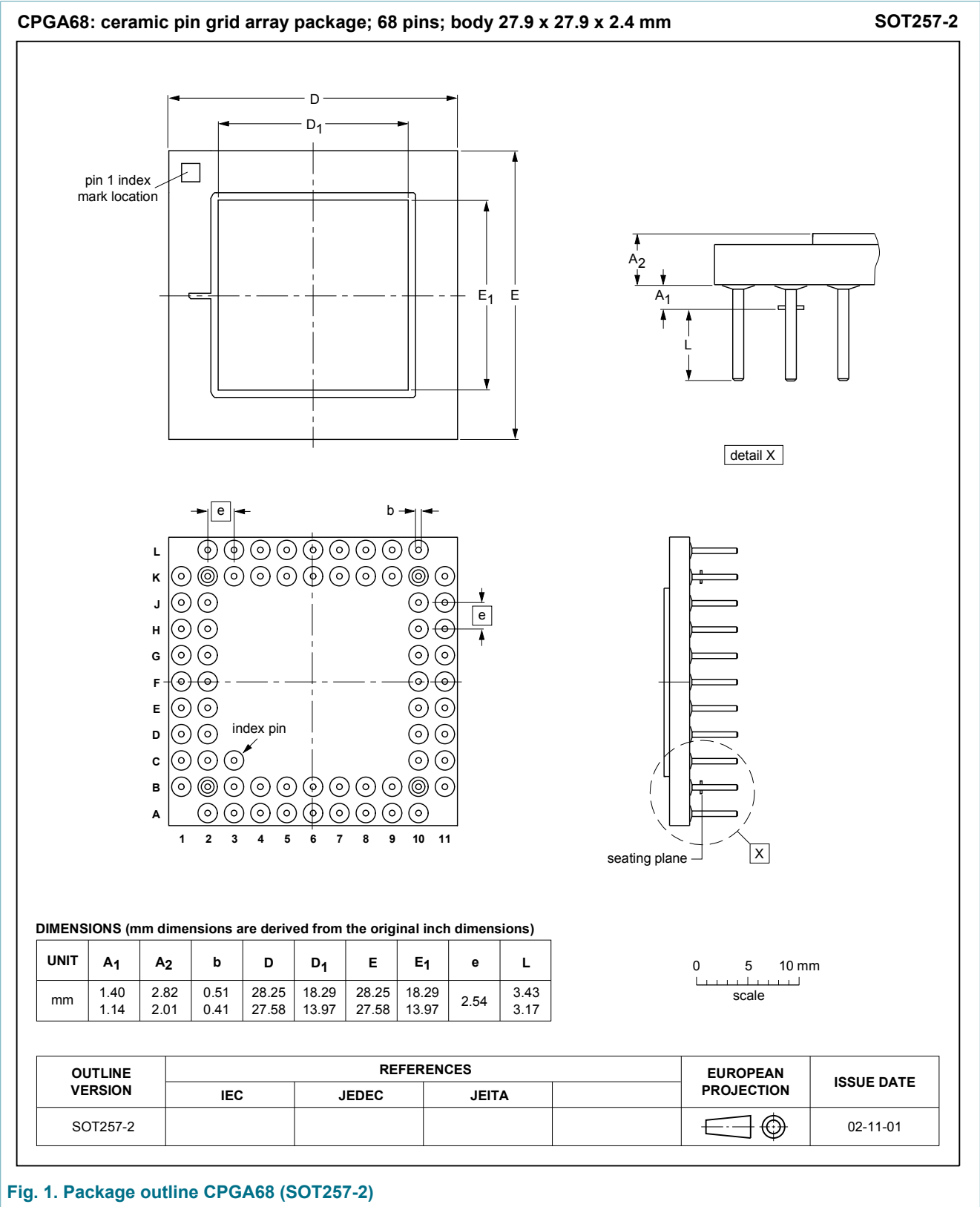
Terminal position code	B (bottom)
Package type descriptive code	CPGA68
Package type industry code	CPGA68
Package style descriptive code	CPGA (ceramic pin grid array)
Package style suffix code	NA (not applicable)
Package body material type	C (ceramic)
Mounting method type	T (through-hole mount)
Issue date	1-11-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		27.58	-	27.9	28.25	mm
E	package width		27.58	-	27.9	28.25	mm
A ₂	package height		2.01	-	2.4	2.82	mm
n ₂	actual quantity of termination		-	-	68	-	



2. Package outline



3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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